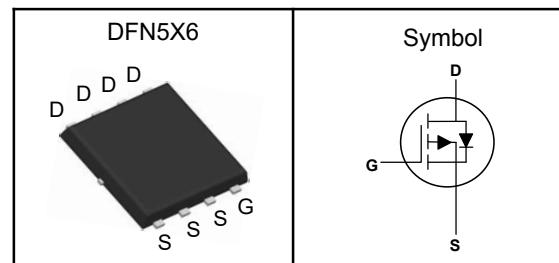


## P-Channel Enhancement Mode MOSFET

### Features

- Fast switching speed
- ROHS Compliant & Halogen-Free
- 100% UIS and R<sub>g</sub> Tested

### Pin Description



### Applications

- Motor drivers
- DC - DC Converter

V <sub>DSS</sub>	-60	V
R <sub>DS(ON)-Typ</sub>	7.4	mΩ
I <sub>D</sub>	-85	A

### Absolute Maximum Ratings (T<sub>J</sub>=25°C, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit	
V <sub>DSS</sub>	Drain-Source Voltage	-60	V	
V <sub>GSS</sub>	Gate-Source Voltage	±20	V	
T <sub>J</sub>	Maximum Junction Temperature	-55 to 150	°C	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C	
I <sub>DM</sub> <sup>①</sup>	Pulse Drain Current Tested	-340	A	
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> =25°C	-85	A
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> =100°C	-53	A
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> =25°C	124	W
E <sub>AS</sub>	Avalanche Energy, Single pulse		287	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	55	°C/W
R <sub>θJC</sub>	Thermal Resistance-Junction to Case	1.02	°C/W

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

## P-Channel Enhancement Mode MOSFET

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-60	---	---	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-60\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	-1	$\mu\text{A}$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.2	---	-2.5	V
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-20\text{A}$	---	7.4	10	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	9.5	13	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=-30\text{V}$ , Freq.=1MHz	---	3880	---	pF
$C_{\text{oss}}$	Output Capacitance		---	635	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	32	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=-10\text{V}$ , $V_{\text{DS}}=-30\text{V}$ , $I_{\text{D}}=-20\text{A}$ , $R_{\text{G}}=3\Omega$	---	4.8	---	nS
$T_{\text{r}}$	Turn-on Rise Time		---	3.1	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	16	---	
$T_{\text{f}}$	Turn-off Fall Time		---	4.1	---	
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{GS}}=-10\text{V}$ , $V_{\text{DS}}=-30\text{V}$ , $I_{\text{D}}=-20\text{A}$	---	59	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	9.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	12	---	
<b>Source-Drain Characteristics</b>						
$I_{\text{s}}$	Maximum Continuous Drain-Source Diode Forward Current	---	---	-85	A	
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{s}}=-20\text{A}$ , $V_{\text{GS}}=0\text{V}$	---	---	-1.2	V

Note ④: Pulse test (pulse width $\leq 300\text{us}$ , duty cycle $\leq 2\%$ ).

Note ⑤ : Guaranteed by design, not subject to production testing.

## P-Channel Enhancement Mode MOSFET

### Typical Characteristics

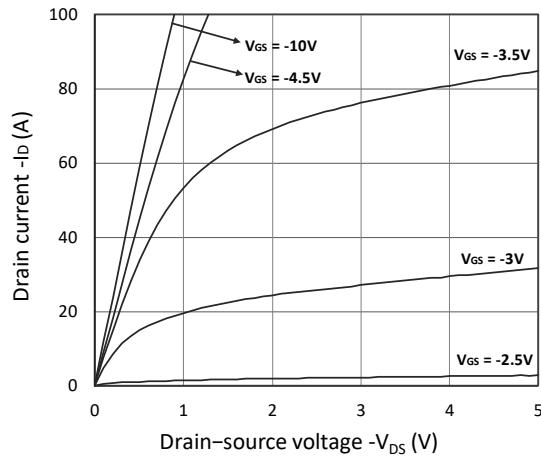


Figure 1. Output Characteristics

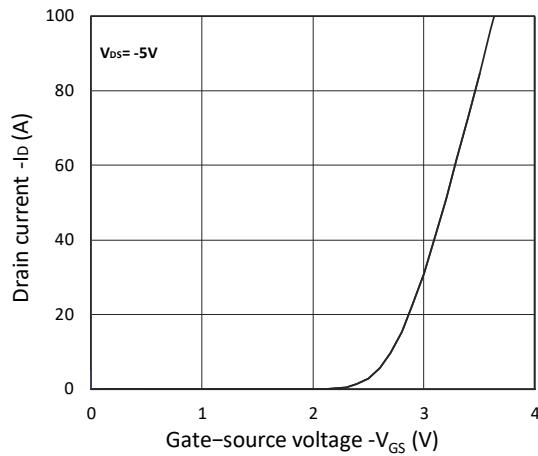


Figure 2. Transfer Characteristics

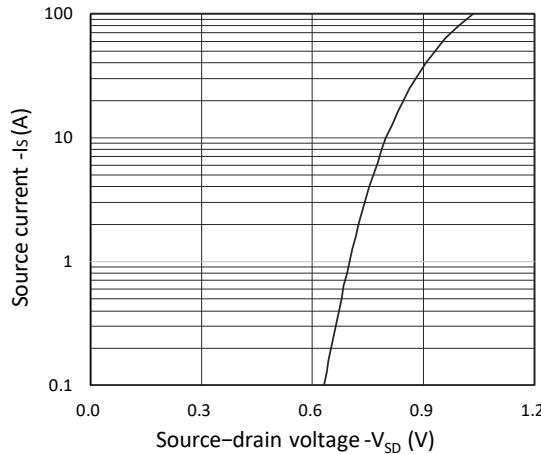


Figure 3. Forward Characteristics of Reverse

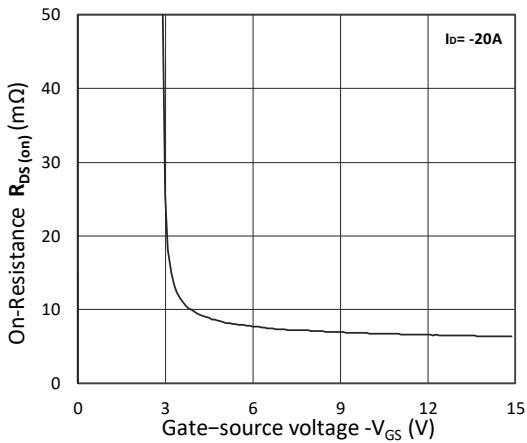


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

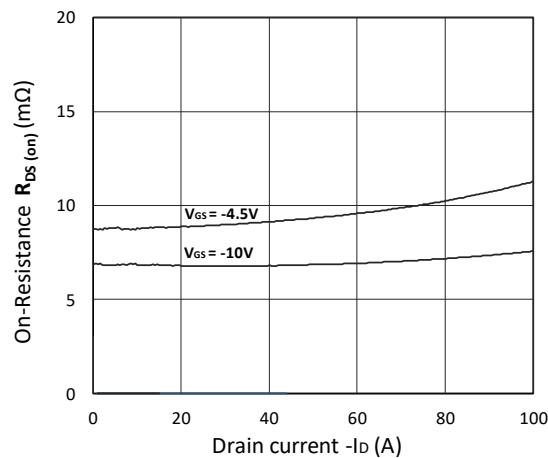


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

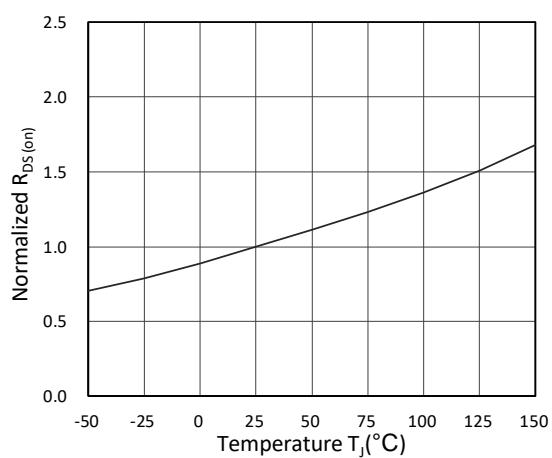


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## P-Channel Enhancement Mode MOSFET

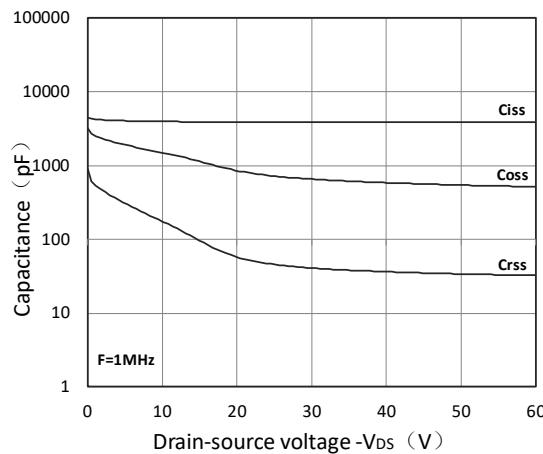


Figure 7. Capacitance Characteristics

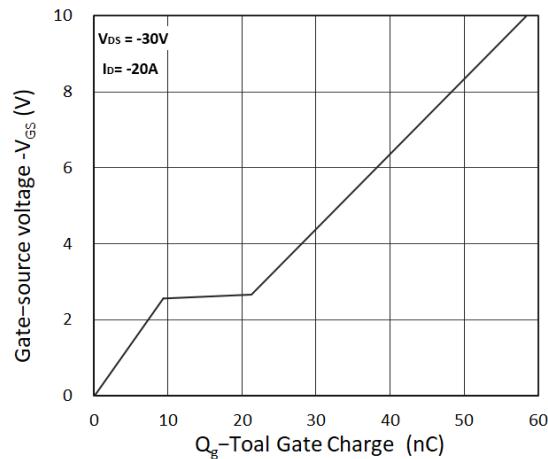


Figure 8. Gate Charge Characteristics

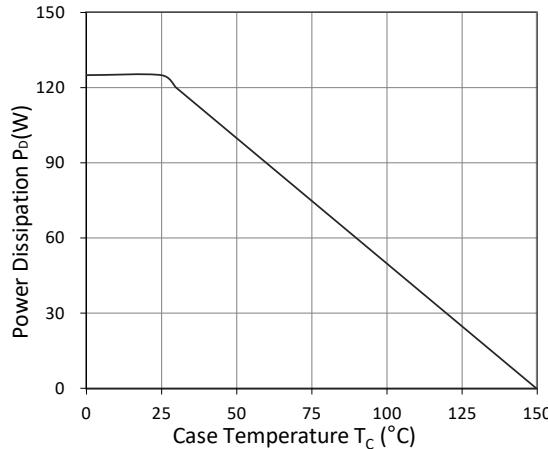


Figure 9. Power Dissipation

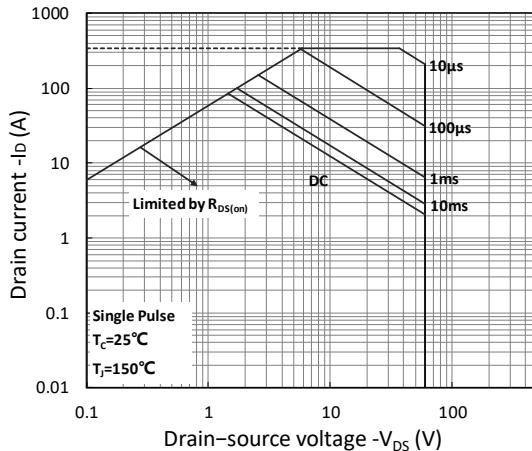


Figure 10. Safe Operating Area

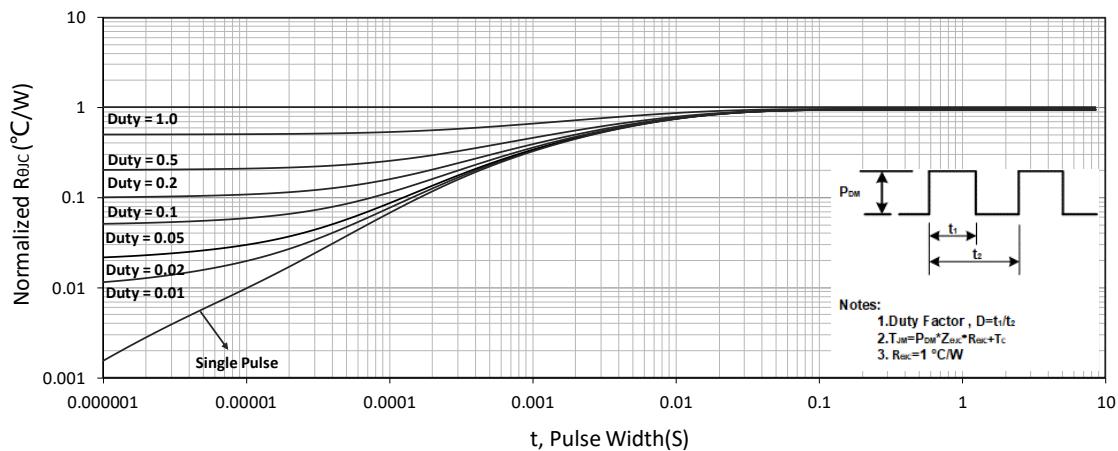
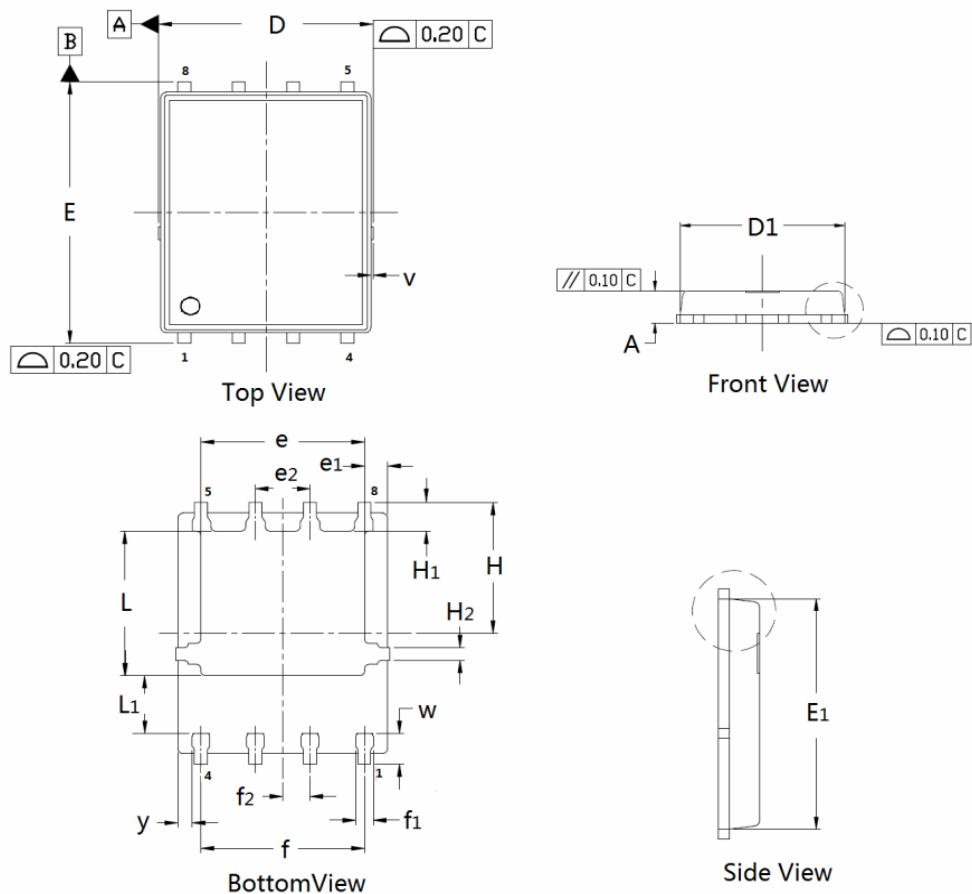


Figure 11. Normalized Maximum Transient Thermal Impedance

## P-Channel Enhancement Mode MOSFET

### DFN5×6 Package Outline Data



**DIMENSIONS (unit : mm)**

Symbol		Typ	Max	Symbol	Min	Typ	Max
<b>A</b>	0.90	1.02	1.10	<b>D</b>	4.90	4.98	5.10
<b>D<sub>1</sub></b>	4.80	4.89	5.10	<b>E</b>	5.90	6.11	6.25
<b>E<sub>1</sub></b>	5.65	5.74	5.95	<b>e</b>	3.72	3.80	3.92
<b>e<sub>1</sub></b>	--	0.5	--	<b>e<sub>2</sub></b>	--	1.	--
<b>f</b>	--	3.8	--	<b>f<sub>1</sub></b>	0.31	0.37	0.51
<b>f<sub>2</sub></b>	--	0.6	--	<b>H</b>	--	3.	--
<b>H<sub>1</sub></b>	0.59	0.63	0.79	<b>H<sub>2</sub></b>	0.26	0.28	0.32
<b>L</b>	3.35	3.45	3.65	<b>L<sub>1</sub></b>	--	1.	--
<b>V</b>	--	0.1	--	<b>w</b>	0.64	0.68	0.84
<b>y</b>	--	0.3	--		--		--



FSL06P074JT

P-Channel Enhancement Mode MOSFET

## 印字说明

### 印字说明

FSL06P074JT

AABBCC

第一行标记为物料型号代码

第二行为AA为内部识别码，BB为表示年份，例如22即表示2022年，CC表示周期，例如01即表示第一周；  
2201即表示2022年第一周生产。